



## Preliminary Product Information Sheet

### **EPO-TEK® T7110-38 (formerly 88-38)**

*Note: These are typical properties to be used as a guide only, not a specification. Data below is not guaranteed. Different batches, conditions and applications yield differing results.*

**Date:** September 2017  
**Rev:** III  
**No. of Components:** Two  
**Mix Ratio by Weight:** 100 : 8.5  
**Specific Gravity:** Part A: 2.40      Part B: 0.99  
**Pot Life:** 30 Minutes  
**Shelf Life- Bulk:** One year at room temperature

**Recommended Cure: 23°C / 2 - 3 Days**

#### **NOTES:**

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.
- Syringe packaging will impact initial viscosity and effective pot life, potentially beyond stated parameters.

**Product Description:** Two component thermally conductive epoxy used for potting and encapsulating.

#### **MATERIAL CHARACTERISTICS\*:**

<b>PHYSICAL PROPERTIES:</b>	<b>Cure condition: varies as required</b>	
Color (before cure):	Part A: Grey	Part B: Clear/Colorless
Consistency:	Smooth paste	
Viscosity (23°C) @ 10 rpm:	18,806	cPs
Thixotropic Index:	2.4	
Glass Transition Temp:	48	°C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)
Shore D Hardness:	88	
Die Shear @ 23°C:	18	Kg
Degradation Temp:	329	°C
Weight Loss:		
	@ 200°C:	0.05 %
	@ 250°C:	0.39 %
	@ 300°C:	1.24 %
Suggested Operating Temperature:	< 250	°C (Intermittent)
Particle Size:	≤ 50	microns

  

<b>ELECTRICAL AND THERMAL PROPERTIES:</b>	
Thermal Conductivity:	1.4 W/mK

**The data above is INITIAL only - it may be changed at any time, for any reason without notice to anyone. It is provided only as a guide for evaluation/consideration.**

\* These material characteristics are typical properties that are based on a limited number of samples/batches. All properties are based on the cure indicated above. Some properties may vary as manufactured quantities are scaled up to commercialized production levels.